

CLAIMS

- [1] A semiconductor laser device comprising:
- a base portion having a horizontal top surface;
- a heat sink portion that has a vertical element mount surface and is located above the top surface of the base portion;
- a semiconductor laser element that is fixed to the element mount surface; and
- a depression that is formed in the top surface of the base portion located immediately below the semiconductor laser element so as to receive part of the semiconductor laser element disposed therein,
- wherein the heat sink portion is fixed to the base portion in such a way that the element mount surface is located inward of an inner side surface of the depression.
- [2] The semiconductor laser device of claim 1,
- wherein the depression is formed within an area of a circle including, on a circumference thereof, a plurality of lead pins that feed a voltage to the semiconductor laser element.
- [3] The semiconductor laser device of claim 1,
- wherein the semiconductor laser element is fixed to the heat sink portion via a submount, part of which is disposed in the depression.
- [4] The semiconductor laser device of claim 1,
- wherein a length of the semiconductor laser element is longer than a height of the heat

sink portion.

- [5] The semiconductor laser device of claim 1,
wherein the base portion and the heat sink portion are formed as a single member.
- [6] The semiconductor laser device of one of claims 1 to 5,
wherein the depression has a rough bottom surface.
- [7] The semiconductor laser device of one of claims 1 to 5,
wherein the depression has an inclined bottom surface.